

IN THE SPECIFICATION

Please amend the specification as shown below. Please replace the paragraph beginning on line 13 at page 13 with the following paragraphs.

--As shown in Figures 2, 3 and 4, blocks 503 and 504 allow process 500 to provide a method for removing heat from an electronic component that includes directing multiple flow streams of a fluid medium (e.g., air) in unique directions with respect to each other towards first ends of at least two sets of multiple fins of an appurtenance coupled to a heat sink and disposed to conduct heat from the electronic component. These directions change within the substantially even spaces between the fins towards a second end of the sets of fins, which is opposite from the first end. As shown in Figures 2, 3 and 4, the flow streams receive motive force from multiple fans, comprising as they do the discharges of the fans, which are disposed and direct their discharges in the unique directions substantially horizontally with respect to the first end of the fins and into the spaces between them.

An embodiment of the present invention, a finned device for removing heat from an electronic component, is thus described. While the present invention has been described in particular embodiments, it should be appreciated that the present invention should not be construed as limited by such embodiments, but rather construed according to the following claims and their equivalents.--